

HD74LS38

Quadruple 2-input Positive NAND Buffers (with Open Collector Outputs)

REJ03D0407-0300 Rev.3.00 Jul.22.2005

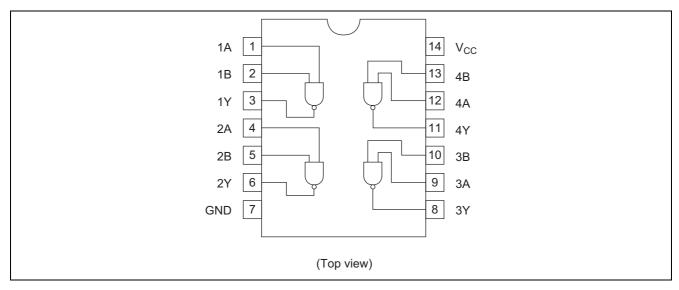
Features

• Ordering Information

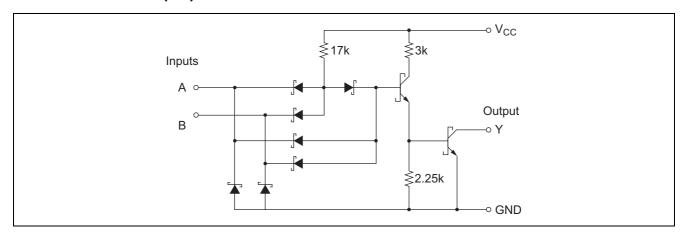
Part Name	Package Type	Package Code (Previous Code)	Package Abbreviation	Taping Abbreviation (Quantity)
HD74LS38P	DILP-14 pin	PRDP0014AB-B (DP-14AV)	Р	_
HD74LS38FPEL	SOP-14 pin (JEITA)	PRSP0014DF-B (FP-14DAV)	FP	EL (2,000 pcs/reel)
HD74LS38RPEL	SOP-14 pin (JEDEC)	PRSP0014DE-A (FP-14DNV)	RP	EL (2,500 pcs/reel)

Note: Please consult the sales office for the above package availability.

Pin Arrangement



Circuit Schematic (1/4)



Absolute Maximum Ratings

Item	Symbol	Ratings	Unit
Supply voltage	Vcc	7	V
Input voltage	V_{IN}	7	V
Power dissipation	P _T	400	mW
Storage temperature	Tstg	-65 to +150	°C

Note: Voltage value, unless otherwise noted, are with respect to network ground terminal.

Recommended Operating Conditions

Item	Symbol	Min	Тур	Max	Unit
Supply voltage	Vcc	4.75	5.00	5.25	V
Output voltage	V _{OH}	_	_	5.5	V
Output current	I _{OL}	_	_	24	mA
Operating temperature	Topr	-20	25	75	°C

Electrical Characteristics

 $(Ta = -20 \text{ to } +75 \text{ }^{\circ}\text{C})$

Item	Symbol	min.	typ.*	max.	Unit	Condition
Input voltage	V _{IH}	2.0		_	V	
Input voltage	V _{IL}	_	_	0.8	V	
Output voltage	V _{OL}	_	_	0.5	V	I _{OL} = 24 mA V _{CC} = 4.75 V, V _{IH} = 2 V
Output voltage		_	_	0.4		$I_{OL} = 12 \text{ mA}$ $VCC = 4.75 \text{ V}, \text{ VIH} = 2 \text{ V}$
Output current	I _{OH}	_	_	250	μΑ	$V_{CC} = 4.75 \text{ V}, V_I = 0.8 \text{ V}, V_{OH} = 5.5 \text{ V}$
	I _{IH}	_	_	20	μΑ	$V_{CC} = 5.25 \text{ V}, V_I = 2.7 \text{ V}$
Input current	I _{IL}	_	_	-0.4	mA	$V_{CC} = 5.25 \text{ V}, V_I = 0.4 \text{ V}$
	l _l	_	_	0.1	mA	$V_{CC} = 5.25 \text{ V}, V_I = 7 \text{ V}$
Cumply ourrant	I _{CCH}	_	0.9	2.0	mA	V _{CC} = 5.25 V
Supply current	I _{CCL}		6	12	mA	V _{CC} = 5.25 V
Input clamp voltage	V _{IK}	_	_	-1.5	V	$V_{CC} = 4.75 \text{ V}, I_{IN} = -18 \text{ mA}$

Note: $^*V_{CC} = 5 \text{ V}, \text{ Ta} = 25^{\circ}\text{C}$

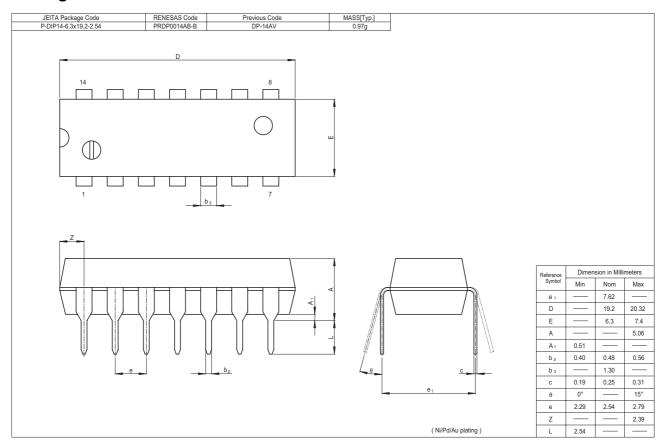
Switching Characteristics

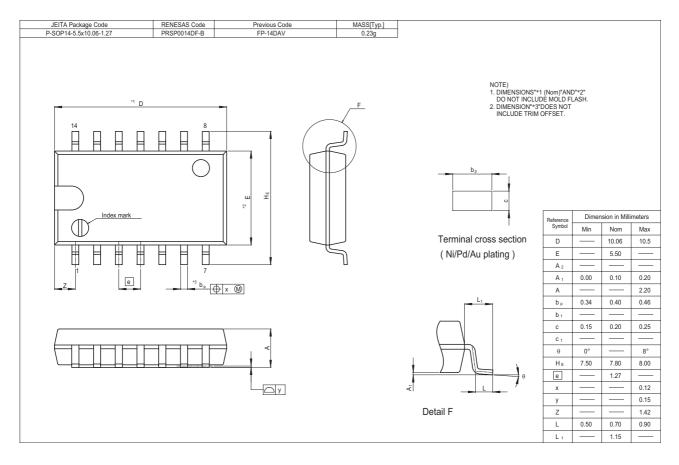
 $(V_{CC} = 5 \text{ V}, \text{ Ta} = 25^{\circ}\text{C})$

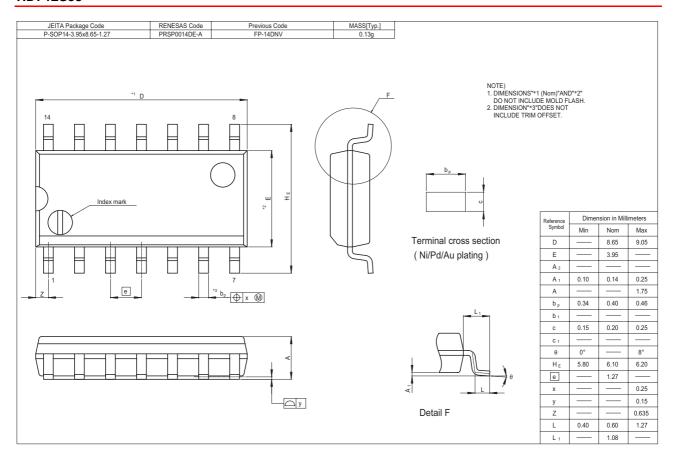
Item	Symbol	min.	typ.	max.	Unit	Condition
Propagation delay time	t _{PLH}	_	20	32	ns	$C_1 = 45 \text{ pF}, R_1 = 667 \Omega$
Propagation delay time	t _{PHL}	_	18	28	ns	$G_{L} = 45 \text{pr}, \text{RL} = 607 \text{S2}$

Note: Refer to Test Circuit and Waveform of the Common Item "TTL Common Matter (Document No.: REJ27D0005-0100)".

Package Dimensions







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